WINSTAR Display

OLED SPECIFICATION

Model No:

WEG010016ABPP5N00100

SPECIFICATION   Version: 0

CUSTOMER   :

MODULE NO. :   **WEG010016ABPP5N00100**

APPROVED BY:

(FOR CUSTOMER USE ONLY)

SALES BY	APPROVED BY	CHECKED BY	PREPARED BY
RELEASE DATE:			

■APPROVAL FOR SPECIFICATIONS ONLY

☐APPROVAL FOR SPECIFICATIONS AND SAMPLE

MODEL NO：

RECORDS OF REVISION			DOC. FIRST ISSUE
VERSION	DATE	REVISED PAGE NO.	SUMMARY
0	2021/04/23		First release

Contents

1.Module Classification Information

W	E	G	010016	A	B	P	P	5	N	0	0	1	00
①	②	③	④	⑤	⑥	⑦	⑧	⑨	⑩	⑪	⑫	⑬	⑭

1	Brand：WINSTAR DISPLAY CORPORATION		
2	E：OLED		
3	Display Type	H：COB Character	G：COB Graphic
		O：COG	F：COG + FR
		P：COG + FR + PCB	X：COF
		A：COG + PCB	N：COF + FR + PCB
4	Dot Matrix： 100 * 16		
5	Serials code		
6	Emitting Color	A：Amber	R：Red	C：Full Color
		B：Blue	W：White	
		G：Green	L：Yellow	
		S：Sky Blue	X：Dual Color	
7	Polarizer	P：With Polarizer; N: Without Polarizer	
		A：Anti-glare Polarizer	
8	Display　Mode	P：Passive Matrix ; N：Active Matrix	
9	Driver Voltage	3：3.0~3.3V　; 　5：5.0V	
10	Touch Panel	N：Without touch panel; T: With touch panel	
11	Product type	0：Standard 1：Daylight Readable 2：Transparent OLED (TOLED) 3：Flexible OLED (FOLED) 4：OLED Lighting	
12	Inspection Grade	0：Standard 2：Special grade C：Automotive grade Y：Consumer grade	
13	Option	0：Default ; 1：COB_6800 ; 2：COB_8080 ; 3：COB_SPI D：Demo Kit ; Z：Semi-customized	
14	Serial No.	Serial number(00~ZZ)	

2.General Specification

Item	Dimension	Unit
Dot Matrix	100*16 Dots	—
Module dimension	80.0 x 36.0 x 10.0(MAX)	mm
View area	66.0 x 16.0	mm
Active area	59.95 x 11.15	mm
Dot size	0.55 x 0.65	mm
Dot pitch	0.60 x 0.70	mm
Panel Type	OLED , Blue	
Duty	1/16	
IC	WS0010-TX	
Interface	6800	
Size	2.4 inch	

3. Contour Drawing & Block Diagram

PIN NO.	SYMBOL
1	VSS
2	VDD
3	NC
4	RS
5	R/W
6	E
7	DB0
8	DB1
9	DB2
10	DB3
11	DB4
12	DB5
13	DB6
14	DB7
15	NC
16	NC

The non-specified tolerance of dimension is ±0.3 mm .

DOT SIZES
SCALE 10/1
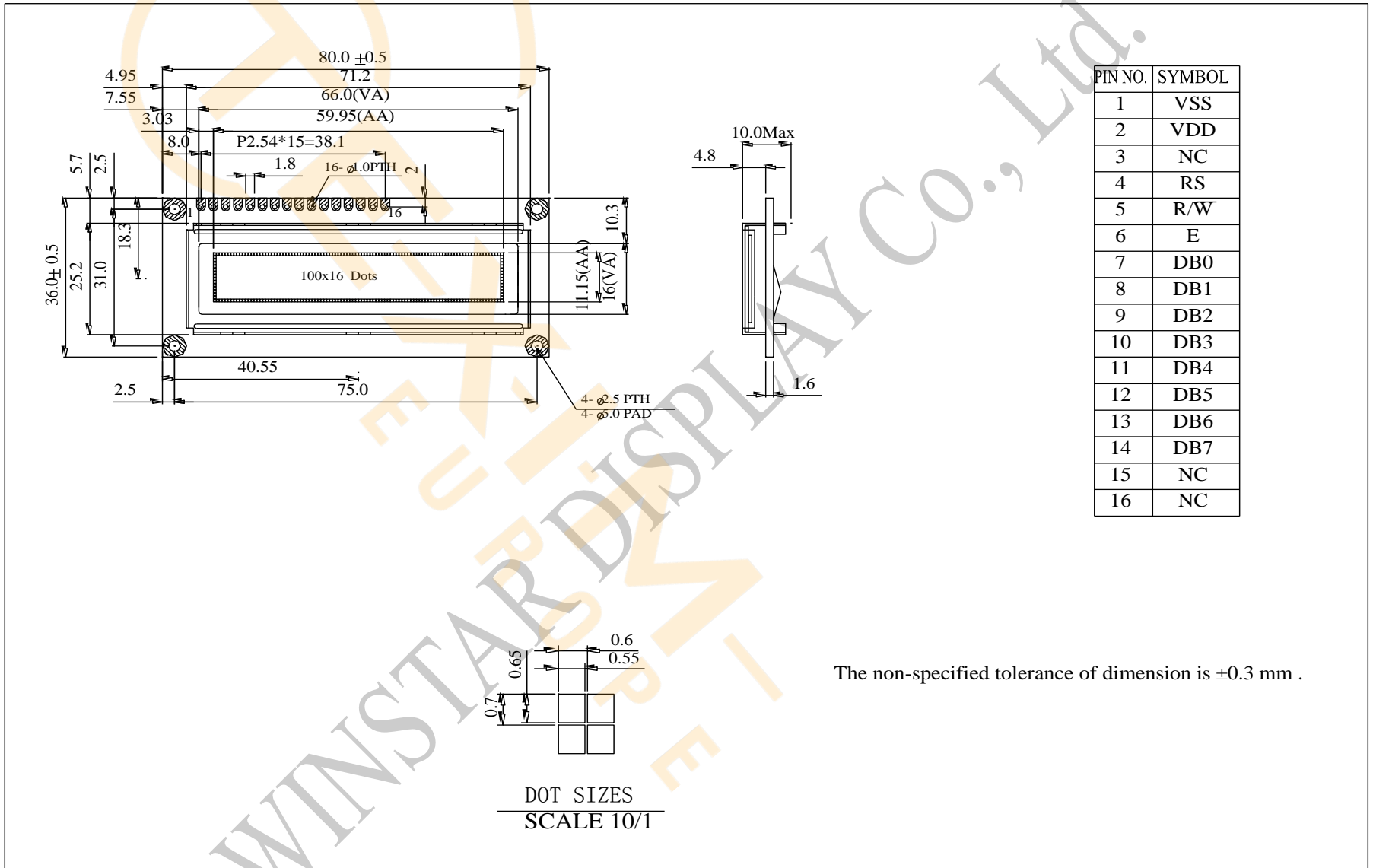
3.1 Application recommendations
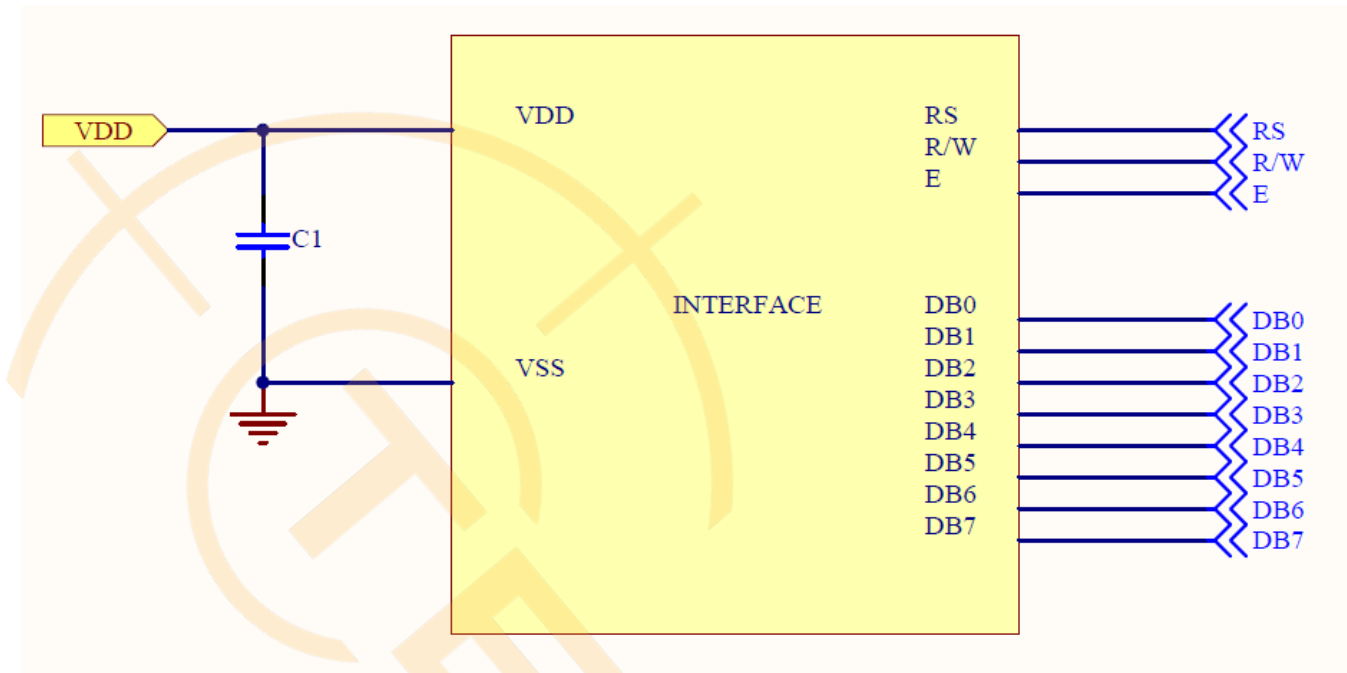
Pin connected to MCU interface: RS, R/W, E, DB0~7

C1：1.0uF [1]

Note
(1) The capacitor value is recommended value. Select appropriate value against module application.

4.Interface Pin Function

Pin No.	Symbol	Level	Description
1	VSS	0V	Ground
2	VDD	5.0V	Supply Voltage for logic
3	NC	—	No connection
4	RS	H/L	H: DATA, L: Instruction code
5	R/W	H/L	H: Read(Module→MPU) L: Write(MPU→Module)
6	E	H,H→L	Chip enable signal
7	DB0	H/L	Data bit 0
8	DB1	H/L	Data bit 1
9	DB2	H/L	Data bit 2
10	DB3	H/L	Data bit 3
11	DB4	H/L	Data bit 4
12	DB5	H/L	Data bit 5
13	DB6	H/L	Data bit 6
14	DB7	H/L	Data bit 7
15	NC	—	No connection
16	NC	—	No connection

5.Absolute Maximum Ratings

Item	Symbol	Min	Max	Unit	Notes
Operating Temperature	TOP	-40	+80	°C	-
Storage Temperature	TST	-40	+85	°C	-
Supply Voltage For Logic	VDD-VSS	-0.3	5.3	V	-

6.Electrical Characteristics

6.1 DC Electrical Characteristics

Item	Symbol	Condition	Min	Typ	Max	Unit
Supply Voltage For Logic	VDD-VSS	─	4.8	5.0	5.3	V
Input High Volt.	VIH	─	0.8xVDD	─	VDD	V
Input Low Volt.	VIL	─	GND	─	0.2xVDD	V
Output High Volt.	VOH	IOH=-0.5mA	0.8xVDD	─	VDD	V
Output Low Volt.	VOL	IOL=0.5mA	GND	─	0.2xVDD	V
50% Check Board Operating Current	IDD	VDD=5V	─	45	67.5	mA

Note: When you use 5V for Vdd please don't use 3V or 3.3V for logic I/O this will cause module does not work.

6.2 Initial code
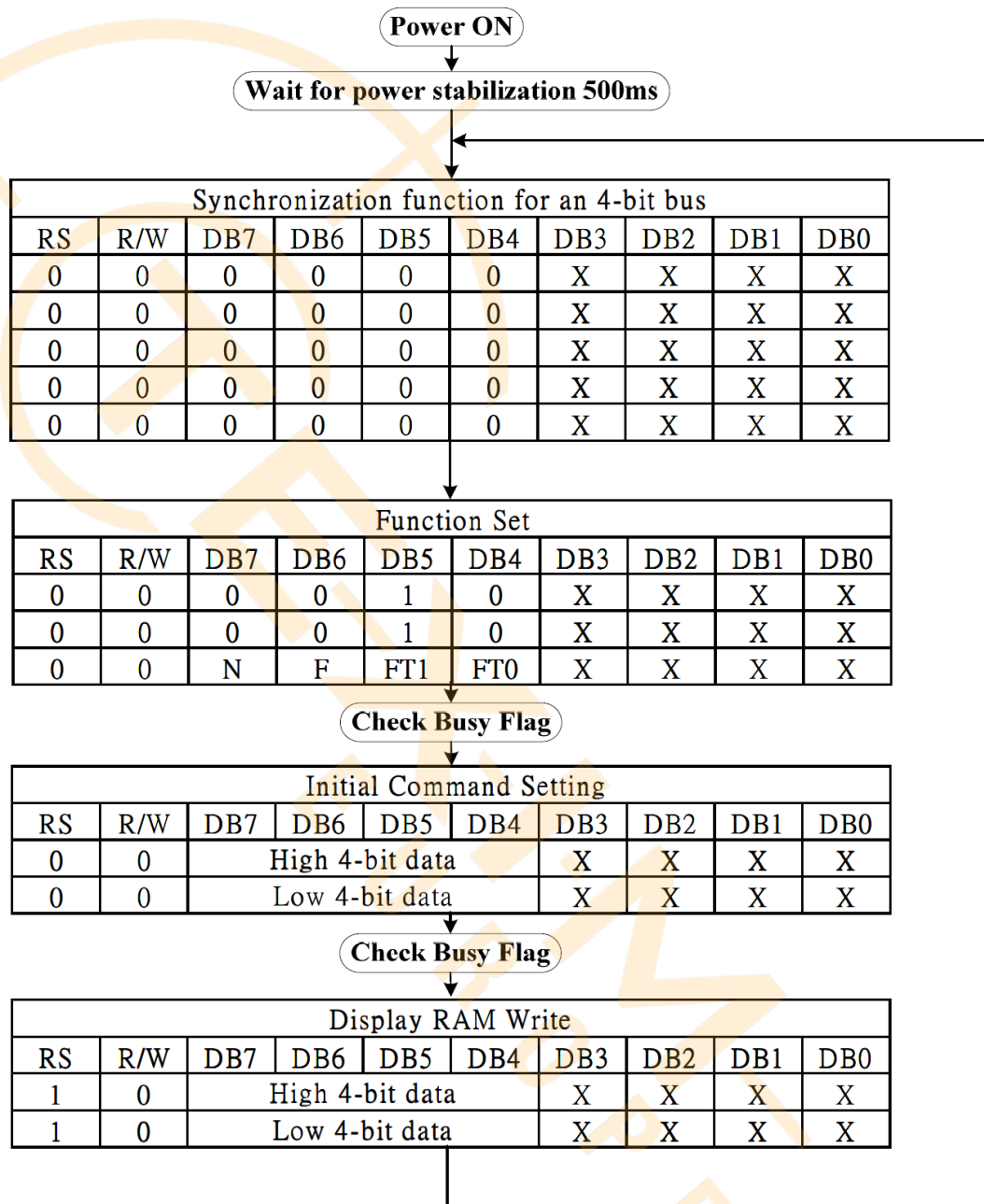
INITIALIZATION BY INSTRUCTION

(1)8-bit mode

Power on

↓

Wait for power stabilization 500ms

↓

function set

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	0	0	1	1	N	F	FT1	FT0

↓

Check Busy Flag

↓

Display ON/OFF Control

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	0	0	0	0	1	D	C	B

↓

Check Busy Flag

↓

Display Clear

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	0	0	0	0	0	0	0	1

↓

Check Busy Flag

↓

Entry Mode Set

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	0	0	0	0	0	1	I/D	SH

↓

Initialization end

(2)4-bit mode

```
┌─────────────────────────┐
│        Power On         │
└─────────────────────────┘
            ↓
┌─────────────────────────────────────┐
│ Wait For Power Stabilization 500ms  │
└─────────────────────────────────────┘
            ↓
```

Function Set									
RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	0	0	1	0	X	X	X	X
0	0	0	0	1	0	X	X	X	X
0	0	N	F	FT1	FT0	X	X	X	X

```
            ↓
┌─────────────────────────┐
│    Check Busy Flay      │
└─────────────────────────┘
            ↓
```

Display ON/OFF Control									
RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	0	0	0	0	X	X	X	X
0	0	1	D	C	B	X	X	X	X

```
            ↓
┌─────────────────────────┐
│    Check Busy Flay      │
└─────────────────────────┘
            ↓
```

Display Clear									
RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	0	0	0	0	X	X	X	X
0	0	0	0	0	1	X	X	X	X

```
            ↓
┌─────────────────────────┐
│    Check Busy Flay      │
└─────────────────────────┘
            ↓
```

Return Home									
RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	0	0	0	0	X	X	X	X
0	0	0	0	1	0	X	X	X	X

```
            ↓
┌─────────────────────────┐
│    Check Busy Flay      │
└─────────────────────────┘
            ↓
```

Entry Mode Set									
RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	0	0	0	0	X	X	X	X
0	0	0	1	I/D	S/H	X	X	X	X

```
            ↓
┌─────────────────────────┐
│    Check Busy Flay      │
└─────────────────────────┘
            ↓
┌─────────────────────────┐
│    Initialization End   │
└─────────────────────────┘
```

Notes
Repeated procedures for an 4-bit bus interface

Noise causing transfer mismatch between the four upper and lower bits can be corrected by a reset triggered by consecutively writing a "0000" instruction five times. The next transfer starts from the lower four bits and then first instruction "Function set" can be executed normally.

Please insert the synchronization function in the head of procedures. The repeated procedures are show as follows :

```
(Power ON)
    ↓
(Wait for power stabilization 500ms)
    ↓
```

Synchronization function for an 4-bit bus

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	0	0	0	0	X	X	X	X
0	0	0	0	0	0	X	X	X	X
0	0	0	0	0	0	X	X	X	X
0	0	0	0	0	0	X	X	X	X
0	0	0	0	0	0	X	X	X	X

Function Set

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	0	0	1	0	X	X	X	X
0	0	0	0	1	0	X	X	X	X
0	0	N	F	FT1	FT0	X	X	X	X

```
(Check Busy Flag)
    ↓
```

Initial Command Setting

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	High 4-bit data				X	X	X	X
0	0	Low 4-bit data				X	X	X	X

```
(Check Busy Flag)
    ↓
```

Display RAM Write

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
1	0	High 4-bit data				X	X	X	X
1	0	Low 4-bit data				X	X	X	X

Note: Initial code is for reference only. Please make the best adjustment with the OLED module.

7.Optical Characteristics

Item	Symbol	Condition	Min	Typ	Max	Unit
View Angle	(V)θ	—	160	—	—	deg
	(H)φ	—	160	—	—	deg
Contrast Ratio	CR	Dark	10,000:1	—	—	—
Response Time	T rise	—	—	10	—	μs
	T fall	—	—	10	—	μs
Display with 50% check Board Brightness			50	70	—	cd/m2
CIEx(Blue)		(CIE1931)	0.12	0.16	0.20	—
CIEy(Blue)		(CIE1931)	0.19	0.23	0.27	—
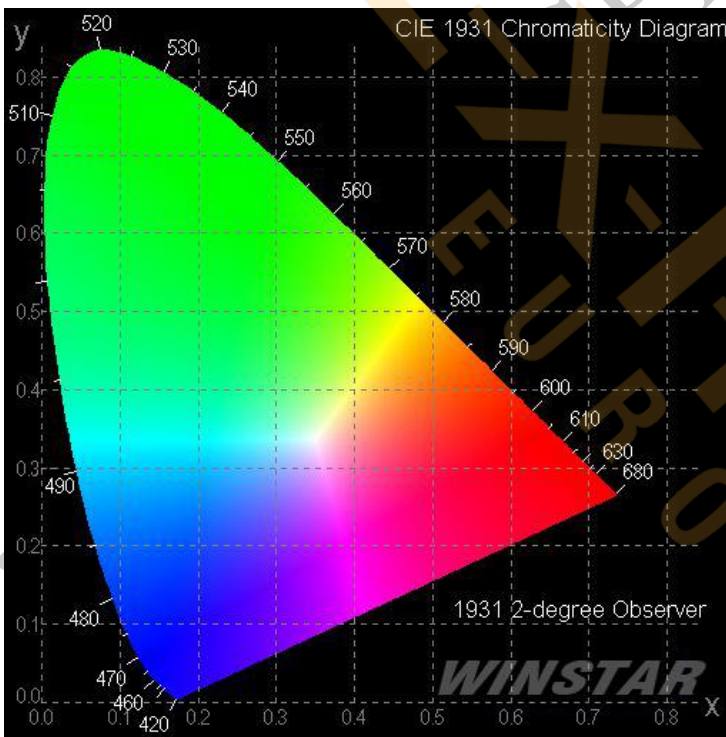
ITEM	Conditions	Min	Typ	Remark
Operating Life Time	Ta=25℃ / Initial 50% check board brightness Typical Value	40,000 Hrs	50,000 Hrs	Note

Notes:
1. Life time is defined the amount of time when the luminance has decayed to <50% of the initial value.
2. This analysis method uses life data obtained under accelerated conditions to extrapolate an estimated probability density function (*pdf*) for the product under normal use conditions.
3. Screen saving mode will extend OLED lifetime.

9.Reliability

Content of Reliability Test

Environmental Test			
Test Item	**Content of Test**	**Test Condition**	**Applicable Standard**
High Temperature storage	Endurance test applying the high storage temperature for a long time.	85°C 240hrs	____
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-40°C 240hrs	____
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	80°C 240hrs	____
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-40°C 240hrs	____
High Temperature/ Humidity Storage	Endurance test applying the high temperature and high humidity storage for a long time.	60°C,90%RH 240hrs	____
High Temperature/ Humidity Operation	Endurance test applying the high temperature and high humidity Operation for a long time.	60°C,90%RH 120hrs	____
Temperature Cycle	Endurance test applying the low and high temperature cycle. -40°C 25°C 80°C 30min 5min 30min	-40°C /80°C 30 cycles	____
Mechanical Test			
Vibration test	Endurance test applying the vibration during transportation and using.	Frequency:10~55Hz amplitude:1.5mm Time:0.5hrs/axis Test axis:X,Y,Z	____
Others			
Static electricity test	Endurance test applying the electric stress to the finished product housing.	Air Discharge model ±4kv,10 times	____

*** Supply voltage for OLED system =Operating voltage at 25°C

Test and measurement conditions

1. All measurements shall not be started until the specimens attain to temperature stability. After the completion of the described reliability test, the samples were left at room temperature for 2 hrs prior to conducting the failure test at 23±5°C; 55±15% RH.
2. All-pixels on/off exchange is used as operation test pattern.
3. The degradation of Polarizer are ignored for High Temperature storage, High Temperature/ Humidity Storage, Temperature Cycle

Evaluation criteria

1. The function test is OK.
2. No observable defects.
3. Luminance: > 50% of initial value.
4. Current consumption: within ± 50% of initial value.

APPENDIX:

RESIDUE IMAGE

Because the pixels are lighted in different time, the luminance of active pixels may reduce or differ from inactive pixels. Therefore, the residue image will occur. To avoid the residue image, every pixel needs to be lighted up uniformly.

WINSTAR

10.Inspection specification

Inspection Standard:
MIL-STD-105E table normal inspection single sample level II.

Definition
1 Major defect : The defect that greatly affect the usability of product.
2 Minor defect : The other defects, such as cosmetic defects, etc.
   Definition of inspection zone:

```
            C
            B

            A
```
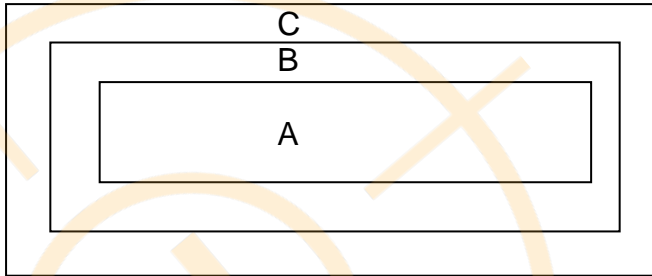
Zone A: Active Area
Zone B: Viewing Area except Zone A
Zone C: Outside Viewing Area
Note: As a general rule, visual defects in Zone C are permissible, when it is no trouble of
      quality and assembly to customer`s product.
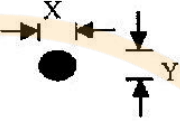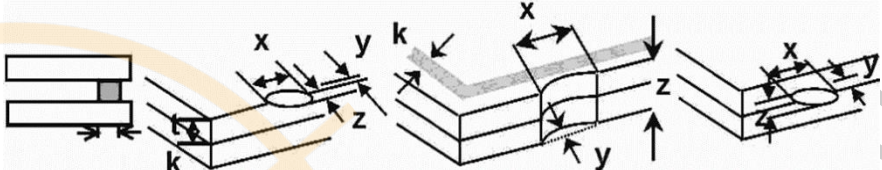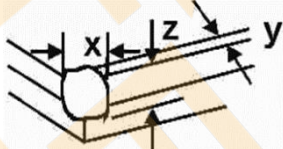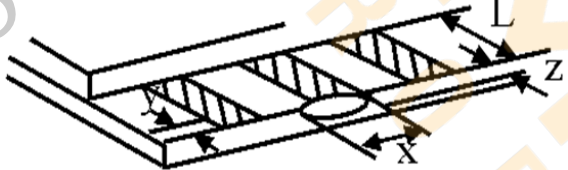
Inspection Methods
1 The general inspection : Under fluorescent light illumination: 750~1500 Lux, about 30cm
 viewing distance, within 45º viewing angle, under 25±5°C.
2 The luminance and color coordinate inspection : By SR-3 or BM-7 or the equal
 equipments, in the dark room, under 25±5°C.
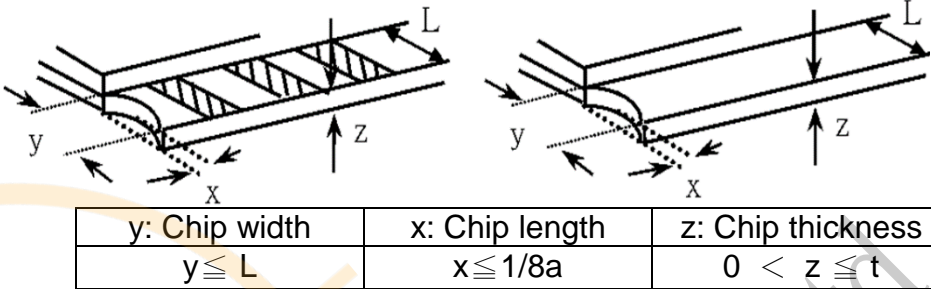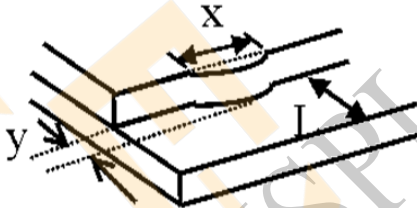
NO	Item	Criterion	AQL
01	Electrical Testing	1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character , dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 OLED viewing angle defect. 1.7 Mixed product types. 1.8 Contrast defect.	0.65
02	Black or white spots on OLED (display only)	2.1 White and black spots on display ≦ 0.25mm, no more than three white or black spots present. 2.2 Densely spaced: No more than two spots or lines within 3mm.	2.5

NO	Item	Criterion				AQL
03	OLED black spots, white spots, contamination (non-display)	3.1 Round type : As following drawing Φ=(x + y) / 2 <table>	2.5

SIZE	Acceptable QTY	Zone
Φ≦0.10	ignore	A+ B,
0.10＜Φ≦0.20	2	A+ B
0.20＜Φ≦0.25	1	A+ B
0.25＜Φ	0	A+ B

3.2 Line type : (As following drawing)

Length	Width	Acceptable Q TY	Zone
---	W≦0.02	ignore	A+B
L≦3.0	0.02＜W≦0.03	2	A+B
L≦2.5	0.03＜W≦0.05		A+B
---	0.05＜W	As round type	

(item 03 AQL = 2.5)

| 04 | Polarizer bubbles /Dent | 4.1 If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction.

Size Φ	Acceptable Q TY	Zone
Φ≦0.20	ignore	A+B
0.20＜Φ≦0.50	3	A+B
0.50＜Φ≦1.00	2	A+B
1.00＜Φ	0	A+B
Total Q TY	3	

4.2 The polarizer dent follows this specification. | 2.5 |

| 05 | Scratches | Follow NO.3 OLED black spots, white spots, contamination. | |

NO	Item	Criterion	AQL
06	Chipped glass	Symbols Define: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: OLED side length L: Electrode pad length: 6.1 General glass chip : 6.1.1 Chip on panel surface and crack between panels: <table><tr><td>z: Chip thickness</td><td>y: Chip width</td><td>x: Chip length</td></tr><tr><td>$Z \leq 1/2t$</td><td>Not over viewing area</td><td>$x \leq 1/8a$</td></tr><tr><td>$1/2t < z \leq 2t$</td><td>Not exceed $1/3k$</td><td>$x \leq 1/8a$</td></tr></table>⊙If there are 2 or more chips, x is total length of each chip. 6.1.2 Corner crack: <table><tr><td>z: Chip thickness</td><td>y: Chip width</td><td>x: Chip length</td></tr><tr><td>$Z \leq 1/2t$</td><td>Not over viewing area</td><td>$x \leq 1/8a$</td></tr><tr><td>$1/2t < z \leq 2t$</td><td>Not exceed $1/3k$</td><td>$x \leq 1/8a$</td></tr></table>⊙If there are 2 or more chips, x is the total length of each chip.	2.5
06	Glass crack	Symbols : x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: OLED side length L: Electrode pad length 6.2 Protrusion over terminal : 6.2.1 Chip on electrode pad : <table><tr><td>y: Chip width</td><td>x: Chip length</td><td>z: Chip thickness</td></tr><tr><td>$y \leq 0.5mm$</td><td>$x \leq 1/8a$</td><td>$0 < z \leq t$</td></tr></table>	2.5

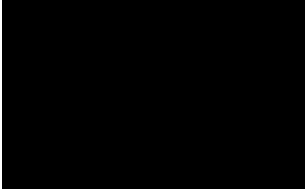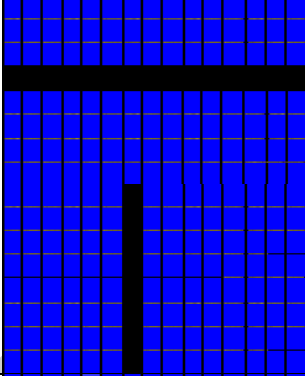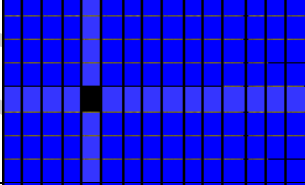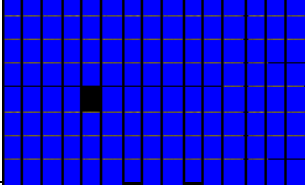| NO	Item	Criterion	AQL
06	Glass crack	6.2.2 Non-conductive portion: <table><tr><td>y: Chip width</td><td>x: Chip length</td><td>z: Chip thickness</td></tr><tr><td>y≦L</td><td>x≦1/8a</td><td>0 < z ≦ t</td></tr></table> ⊙If the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. ⊙If the product will be heat sealed by the customer, the alignment mark not be damaged. 6.2.3 Substrate protuberance and internal crack. <table><tr><td>y: width</td><td>x: length</td></tr><tr><td>y≦1/3L</td><td>x ≦ a</td></tr></table> 	2.5
07	Cracked glass	The OLED with extensive crack is not acceptable.	2.5
08	Backlight elements	8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using OLED spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong.	0.65 2.5 0.65
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination. 9.2 Bezel must comply with job specifications.	2.5 0.65
10	PCB , COB	10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, OLED pad, zebra pad or	2.5 2.5 0.65 2.5 2.5 0.65 0.65 2.5
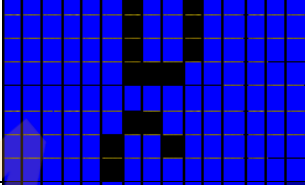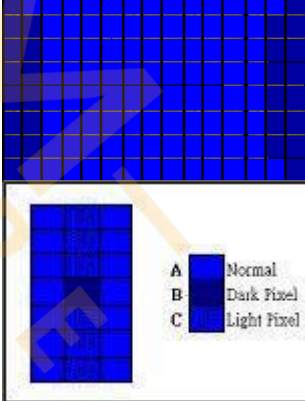
		screw hold pad, make sure it is smoothed down.	

NO	Item	Criterion	AQL
11	Soldering	11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB.	2.5 2.5 2.5 0.65
12	General appearance	12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP. 12.2 No cracks on interface pin (OLB) of TCP. 12.3 No contamination, solder residue or solder balls on product. 12.4 The IC on the TCP may not be damaged, circuits. 12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever. 12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color. 12.7 Sealant on top of the ITO circuit has not hardened. 12.8 Pin type must match type in specification sheet. 12.9 OLED pin loose or missing pins. 12.10 Product packaging must the same as specified on packaging specification sheet. 12.11 Product dimension and structure must conform to product specification sheet.	2.5 0.65 2.5 2.5 2.5 2.5 2.5 0.65 0.65 0.65 0.65

| Check Item	Classification	Criteria
No Display	Major	
Missing Line	Major	
Pixel Short	Major	
Darker Short	Major	
Wrong Display	Major	
Un-uniform B/A x 100% < 70% A/C x 100% < 70%	Major	A Normal B Dark Pixel C Light Pixel

Modules

(1) Avoid applying excessive shocks to module or making any alterations or modifications to it.
(2) Don't make extra holes on the printed circuit board, change the components or modify its shape of OLED display module.
(3) Don't disassemble the OLED display module.
(4) Do not apply input signals while the logic power is off.
(5) Don't operate it above the absolute maximum rating.
(6) Don't drop, bend or twist OLED display module.
(7) Soldering: only to the I/O terminals.
(8) Hot-Bar FPC soldering condition: 280~350C, less than 5 seconds.
(9) Winstar has the right to change the passive components (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.) and change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Winstar have the right to modify the version.)
(10) Winstar has the right to upgrade or modify the product function.
(11) For COG & COF structure OLED products, customers should reserve VCC (VPP) adjustment function or software update function when designing OLED supporting circuit. (The progress of OLED light-emitting materials will increase the conversion efficiency and the brightness. The brightness can be adjusted if necessary).

11.1. Handling Precautions

(1) Since the display panel is being made of glass, do not apply mechanical impacts such as dropping from a high position.
(2) If the display panel is broken by some accident and the internal organic substance leaks out, be careful not to inhale nor lick the organic substance.
(3) If pressure is applied to the display surface or its neighborhood of the OLED display module, the cell structure may be damaged. So, be careful not to apply pressure to these sections.
(4) The polarizer covering the surface of the OLED display module is soft and easily scratched.
(5) When the surface of the polarizer of the OLED display module has soil, clean the surface. It takes advantage by using following adhesion tape.
   * Scotch Mending Tape No. 810 or an equivalent
   Never try to breathe upon the soiled surface nor wipe the surface using cloth containing solvent such as ethyl alcohol, since the surface of the polarizer will become cloudy.
   Also, pay attention that the following liquid and solvent may spoil the polarizer:
   * Water
   * Ketone
   * Aromatic Solvents
(6) Protection film is being applied to the surface of the display panel and removes the protection film before assembling it. At this time, if the OLED display module has been stored for a long period of time, residue adhesive material of the protection film may remain on the surface of the display panel after removed of the film. In such case, remove the residue material by the method introduced in the above Section 5.
(7) Do not touch the following sections whenever possible while handling the OLED display modules.
   * Pins and electrodes

* Pattern layouts such as the TCP & FPC

(8) Hold OLED display module very carefully when placing OLED display module into the System housing. Do not apply excessive stress or pressure to OLED display module. And, do not over bend the film with electrode pattern layouts. These stresses will influence the display performance. Also, secure sufficient rigidity for the outer cases.
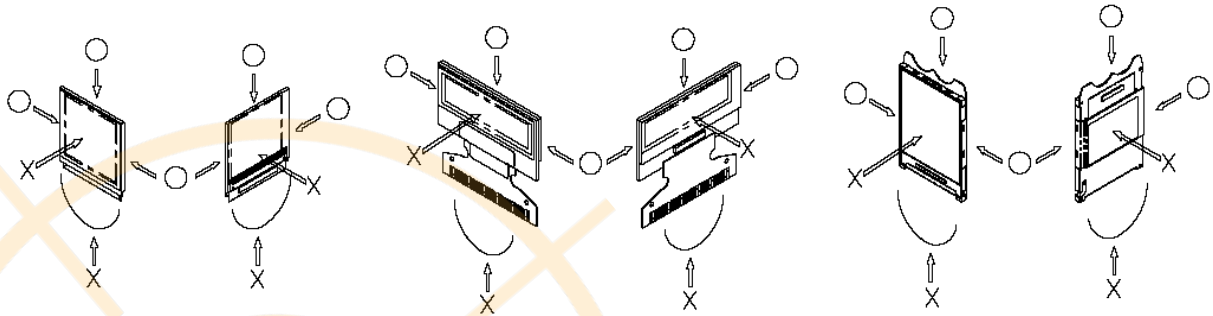
(9) Do not apply stress to the LSI chips and the surrounding molded sections.

(10) Pay sufficient attention to the working environments when handing OLED display modules to prevent occurrence of element breakage accidents by static electricity.

* Be sure to make human body grounding when handling OLED display modules.

* Be sure to ground tools to use or assembly such as soldering irons.

* To suppress generation of static electricity, avoid carrying out assembly work under dry environments.

* Protective film is being applied to the surface of the display panel of the OLED display module. Be careful since static electricity may be generated when exfoliating the protective film.

11.2. Storage Precautions

(1) When storing OLED display modules, put them in static electricity preventive bags to avoid be directly exposed to sun or lights of fluorescent lamps. And, also, place in the temperature 25±5°C and Humidity below 65% RH.(We recommend you to store these modules in the packaged state when they were shipped from Winstar. At that time, be careful not to let water drops adhere to the packages or bags.)

(2) When the OLED display module is being dewed or when it is placed under high temperature or high humidity environments, the electrodes may be corroded if electric current is applied. Please store it in clean environment.

11.3. Designing Precautions

(1) The absolute maximum ratings are the ratings which cannot be exceeded for OLED display module, and if these values are exceeded, OLED display module may be damaged.

(2) To prevent occurrence of malfunctioning by noise, pay attention to satisfy the VIL and VIH specification and to make the signal line cable as short as possible.

(3) We recommend you to install excess current preventive unit (fuses, etc.) to the power circuit (VDD / VCC). (Recommend value: 0.5A)

(4) Pay sufficient attention to avoid occurrence of mutual noise interference with the nearby devices.

(5) As for EMI, take necessary measures on the equipment side basically.

(6) If the power supplied to the OLED display module is forcibly shut down by such errors as taking out the main battery while the OLED display panel is in operation, we cannot guarantee the quality of this OLED display module.

* Connection (contact) to any other potential than the above may lead to rupture of the IC.

(7) If this OLED driver is exposed to light, malfunctioning may occur and semiconductor elements may change their characteristics.

(8) The internal status may be changed, if excessive external noise enters into the module. Therefore, it is necessary to take appropriate measures to suppress noise generation or to protect module from influences of noise on the system design.

(9) We recommend you to make periodical refreshment of the operation statuses (re-setting of the commands and re-transference of the display data) to cope with catastrophic noise.

(10) It's pretty common to use "Screen Saver" to extend the lifetime and Don't use the same image for long time in real application. When an OLED display module is operated for a long of time with fixed pattern, an afterimage or slight contrast deviation may occur.

(11) The limitation of FPC and Film bending.
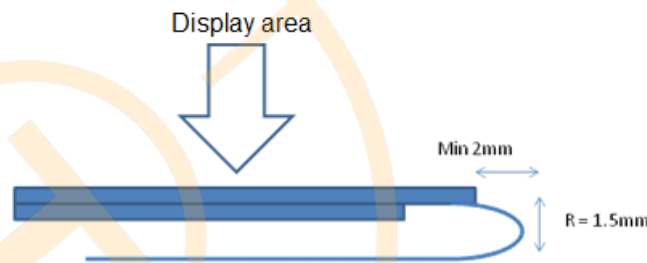
(12) The module should be fixed balanced into the housing, or the module may be twisted.
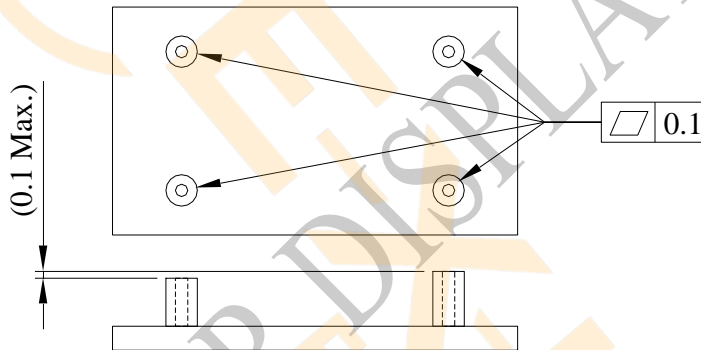
(13) Please heat up a little the tape sticking on the components when removing it; otherwise the components might be damaged.

11.4. Precautions when disposing of the OLED display modules

(1) Request the qualified companies to handle industrial wastes when disposing of the OLED display modules. Or, when burning them, be sure to observe the environmental and hygienic laws and regulations.

Contact details

The Netherlands

Elektrostraat 17
NL-7483 PG Haaksbergen

T: +31 (0)53 573 33 33
F: +31 (0)53 573 33 30
E: nl@texim-europe.com

Belgium

Zuiderlaan 14 bus 10
B-1731 Zellik

T: +32 (0)2 462 01 00
F: +32 (0)2 462 01 25
E: belgium@texim-europe.com

UK & Ireland

St. Mary's House, Church Lane
Carlton Le Moorland
Lincoln LN5 9HS

T: +44 (0)1522 789 555
F: +44 (0)845 299 22 26
E: uk@texim-europe.com

Germany North

Bahnhofstrasse 92
D-25451 Quickborn

T: +49 (0)4106 627 07-0
F: +49 (0)4106 627 07-20
E: germany@texim-europe.com

Germany South

Martin-Kollar-Strasse 9
D-81829 München

T: +49 (0)89 436 086-0
F: +49 (0)89 436 086-19
E: germany@texim-europe.com

Austria

Warwitzstrasse 9
A-5020 Salzburg

T: +43 (0)662 216 026
F: +43 (0)662 216 026-66
E: austria@texim-europe.com

Nordic region

Sdr. Jagtvej 12
DK-2970 Hørsholm

T: +45 88 20 26 30
F: +45 88 20 26 39
E: nordic@texim-europe.com

Italy

Via Matteotti 43
IT-20864 Agrate Brianza (MB)

T: +39 (0)39 971 3293
F: +39 (0)39 971 3293
E: italy@texim-europe.com

General information

info@texim-europe.com
www.texim-europe.com

member of the TKH Group